Advanced FIB Circuit Edit – Back Side Sample Application Training
Abbreviated* Syllabus.

1. Planning backside circuit modification, aspect ratio and distance considerations;
2. Sample preparation, thermal conditioning, drift reduction;
3. Advanced backside navigation: precision lock, beam placement, drift compensation;
4. Die distortion issues;
5. Basics of Gas Assisted Etching (GAE) theory, advanced GAE techniques;
6. Choice of apertures, beam currents, imaging modes
7. Local Si thinning and endpoint detection, voltage contrast and beam induced current;
8. Via endpoint concept and advanced detection methods;
9. Via filling, dielectric and conductor deposition;
10. Specifics of Cu technology;
11. High Aspect Ratio (HAR) probe points;

*Detailed syllabus is available upon request sent to: info@partbeamsystech.com

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